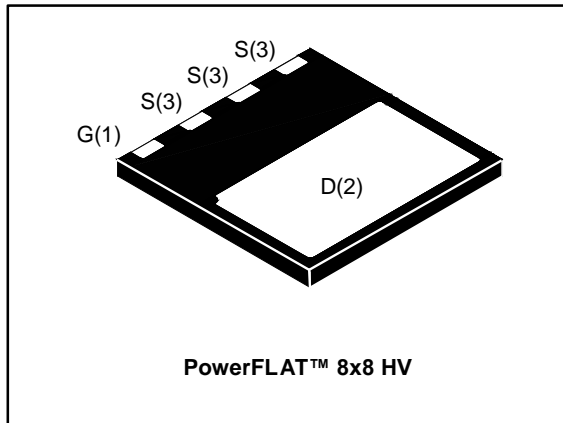
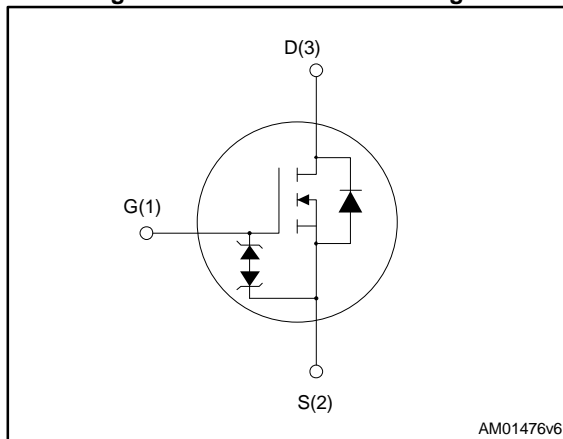


## N-channel 650 V, 0.205 $\Omega$ typ., 14 A MDmesh M2 Power MOSFET in a PowerFLAT™ 8x8 HV package

Datasheet - production data



**Figure 1: Internal schematic diagram**



### Features

| Order codes | V <sub>DS</sub> | R <sub>DS(on)</sub> max | I <sub>D</sub> |
|-------------|-----------------|-------------------------|----------------|
| STL24N65M2  | 650 V           | 0.250 $\Omega$          | 14 A           |

- Extremely low gate charge
- Excellent output capacitance (C<sub>oss</sub>) profile
- 100% avalanche tested
- Zener-protected

### Applications

- Switching applications

### Description

This device is an N-channel Power MOSFET developed using MDmesh™ M2 technology. Thanks to its strip layout and improved vertical structure, the devices exhibit low on-resistance and optimized switching characteristics, rendering it suitable for the most demanding high efficiency converters.

**Table 1: Device summary**

| Order codes | Marking | Package           | Packaging     |
|-------------|---------|-------------------|---------------|
| STL24N65M2  | 24N65M2 | PowerFLAT™ 8x8 HV | Tape and reel |

---

## Contents

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# 1 Electrical ratings

**Table 2: Absolute maximum ratings**

| Symbol         | Parameter   | Value       | Unit             |
|----------------|---|-------------|------------------|
| $V_{GS}$       | Gate-source voltage   | $\pm 25$    | V                |
| $I_D$          | Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$  | 14          | A                |
| $I_D$          | Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$ | 8.8         | A                |
| $I_{DM}^{(1)}$ | Drain current (pulsed)  | 56          | A                |
| $P_{TOT}$      | Total dissipation at $T_C = 25\text{ }^\circ\text{C}$           | 125         | W                |
| $dv/dt^{(2)}$  | Peak diode recovery voltage slope                               | 15          | V/ns             |
| $dv/dt^{(3)}$  | MOSFET $dv/dt$ ruggedness                                       | 50          | V/ns             |
| $T_{stg}$      | Storage temperature   | - 55 to 150 | $^\circ\text{C}$ |
| $T_j$          | Max. operating junction temperature                             |             |                  |

**Notes:**

(1)Pulse width limited by safe operating area.

(2) $I_{SD} \leq 14\text{ A}$ ,  $di/dt \leq 400\text{ A}/\mu\text{s}$ ;  $V_{DS(\text{peak})} < V_{(BR)DSS}$ ,  $V_{DD} = 80\% V_{(BR)DSS}$ .

(3) $V_{DS} \leq 520\text{ V}$

**Table 3: Thermal data**

| Symbol                | Parameter  | Value | Unit                      |
|-----------------------|--|-------|---------------------------|
| $R_{thj\text{-case}}$ | Thermal resistance junction-case max               | 1     | $^\circ\text{C}/\text{W}$ |
| $R_{thj\text{-pcb}}$  | Thermal resistance junction-pcb max <sup>(1)</sup> | 50    | $^\circ\text{C}/\text{W}$ |

**Notes:**

(1)When mounted on 1 inch<sup>2</sup> FR-4, 2 Oz copper board.

**Table 4: Avalanche characteristics**

| Symbol   | Parameter  | Value | Unit |
|----------|--|-------|------|
| $I_{AR}$ | Avalanche current, repetitive or not repetitive (pulse width limited by $T_{j\text{max}}$ )                    | 2     | A    |
| $E_{AS}$ | Single pulse avalanche energy (starting $T_j=25\text{ }^\circ\text{C}$ , $I_D= I_{AR}$ ; $V_{DD}=50\text{V}$ ) | 655   | mJ   |

## 2 Electrical characteristics

( $T_C = 25\text{ °C}$  unless otherwise specified)

**Table 5: On /off states**

| Symbol        | Parameter   | Test conditions                                    | Min. | Typ.  | Max.     | Unit          |
|---------------|---|--|------|-------|----------|---------------|
| $V_{(BR)DSS}$ | Drain-source breakdown voltage                            | $I_D = 1\text{ mA}$ , $V_{GS} = 0\text{ V}$        | 650  |       |          | V             |
| $I_{DSS}$     | Zero gate voltage drain current ( $V_{GS} = 0\text{ V}$ ) | $V_{DS} = 650\text{ V}$                            |      |       | 1        | $\mu\text{A}$ |
|               |   | $V_{DS} = 650\text{ V}$ , $T_C = 125\text{ °C}$    |      |       | 100      | $\mu\text{A}$ |
| $I_{GSS}$     | Gate-body leakage current ( $V_{DS} = 0\text{ V}$ )       | $V_{GS} = \pm 25\text{ V}$                         |      |       | $\pm 10$ | $\mu\text{A}$ |
| $V_{GS(th)}$  | Gate threshold voltage                                    | $V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$ | 2    | 3     | 4        | V             |
| $R_{DS(on)}$  | Static drain-source on-resistance                         | $V_{GS} = 10\text{ V}$ , $I_D = 7\text{ A}$        |      | 0.205 | 0.250    | $\Omega$      |

**Table 6: Dynamic**

| Symbol                     | Parameter                     | Test conditions   | Min. | Typ. | Max. | Unit     |
|----------------------------|-------------------------------|---|------|------|------|----------|
| $C_{iss}$                  | Input capacitance             | $V_{DS} = 100\text{ V}$ , $f = 1\text{ MHz}$ ,<br>$V_{GS} = 0\text{ V}$   | -    | 1060 | -    | pF       |
| $C_{oss}$                  | Output capacitance            |   | -    | 47.5 | -    | pF       |
| $C_{rss}$                  | Reverse transfer capacitance  |   | -    | 1.65 | -    | pF       |
| $C_{oss\text{ eq.}}^{(1)}$ | Equivalent output capacitance | $V_{DS} = 0\text{ to }520\text{ V}$ ,<br>$V_{GS} = 0\text{ V}$            | -    | 229  | -    | pF       |
| $R_G$                      | Intrinsic gate resistance     | $f = 1\text{ MHz}$ , $I_D = 0$  | -    | 7    | -    | $\Omega$ |
| $Q_g$                      | Total gate charge             | $V_{DD} = 520\text{ V}$ , $I_D = 16\text{ A}$ ,<br>$V_{GS} = 10\text{ V}$ | -    | 29   | -    | nC       |
| $Q_{gs}$                   | Gate-source charge            |   | -    | 3.8  | -    | nC       |
| $Q_{gd}$                   | Gate-drain charge             |   | -    | 14   | -    | nC       |

**Notes:**

<sup>(1)</sup>  $C_{oss\text{ eq.}}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$

**Table 7: Switching times**

| Symbol       | Parameter           | Test conditions  | Min. | Typ. | Max. | Unit |
|--------------|---------------------|--|------|------|------|------|
| $t_{d(on)}$  | Turn-on delay time  | $V_{DD} = 325\text{ V}$ , $I_D = 8\text{ A}$ ,<br>$R_G = 4.7\text{ }\Omega$ , $V_{GS} = 10\text{ V}$ | -    | 10   | -    | ns   |
| $t_r$        | Rise time           |  | -    | 9.5  | -    | ns   |
| $t_{d(off)}$ | Turn-off delay time |  | -    | 68   | -    | ns   |
| $t_f$        | Fall time           |  | -    | 25.5 | -    | ns   |

Table 8: Source drain diode

| Symbol          | Parameter                     | Test conditions   | Min. | Typ. | Max. | Unit          |
|-----------------|-------------------------------|---|------|------|------|---------------|
| $I_{SD}$        | Source-drain current          |   | -    |      | 16   | A             |
| $I_{SDM}^{(1)}$ | Source-drain current (pulsed) |   | -    |      | 64   | A             |
| $V_{SD}^{(2)}$  | Forward on voltage            | $I_{SD} = 16 \text{ A}$ , $V_{GS} = 0 \text{ V}$  | -    |      | 1.6  | V             |
| $t_{rr}$        | Reverse recovery time         | $I_{SD} = 16 \text{ A}$ , $di/dt = 100 \text{ A}/\mu\text{s}$<br>$V_{DD} = 60 \text{ V}$                                      | -    | 350  |      | ns            |
| $Q_{rr}$        | Reverse recovery charge       |   | -    | 4.5  |      | $\mu\text{C}$ |
| $I_{RRM}$       | Reverse recovery current      |   | -    | 26   |      | A             |
| $t_{rr}$        | Reverse recovery time         | $I_{SD} = 16 \text{ A}$ , $di/dt = 100 \text{ A}/\mu\text{s}$<br>$V_{DD} = 60 \text{ V}$ , $T_j = 150 \text{ }^\circ\text{C}$ | -    | 496  |      | ns            |
| $Q_{rr}$        | Reverse recovery charge       |   | -    | 6.5  |      | $\mu\text{C}$ |
| $I_{RRM}$       | Reverse recovery current      |   | -    | 25.5 |      | A             |

**Notes:**

(1)Pulse width limited by safe operating area.

(2)Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%

## 2.1 Electrical characteristics (curves)

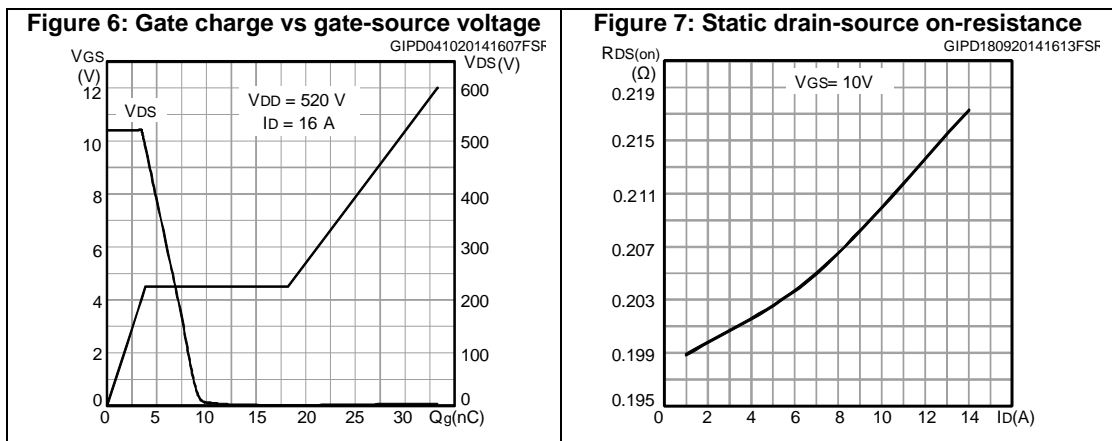
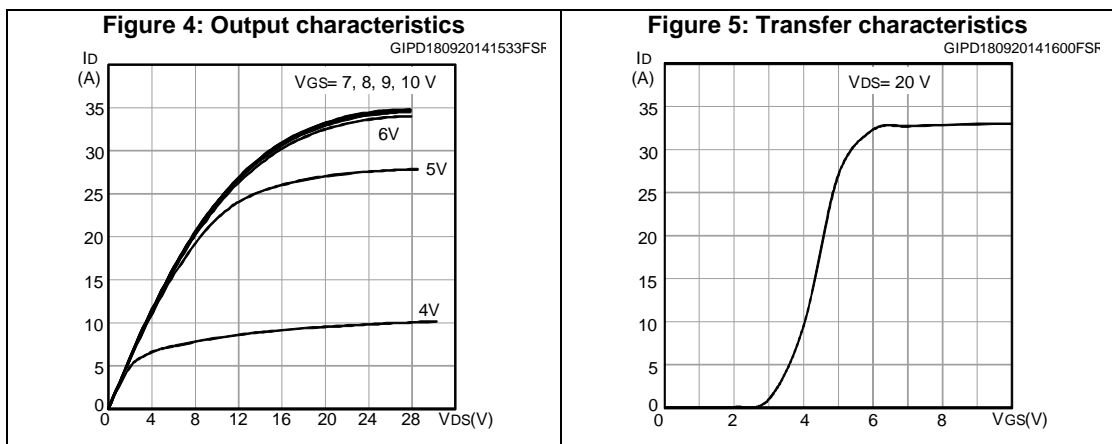
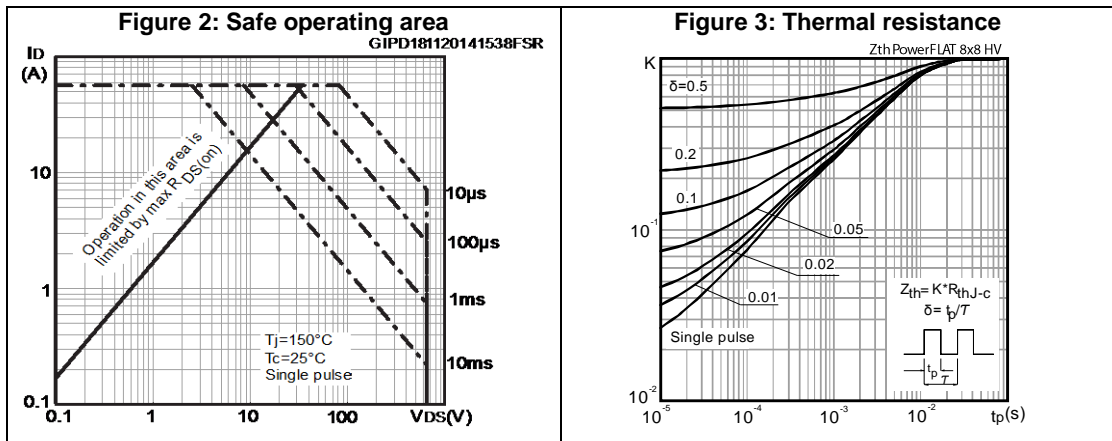


Figure 8: Capacitance variations

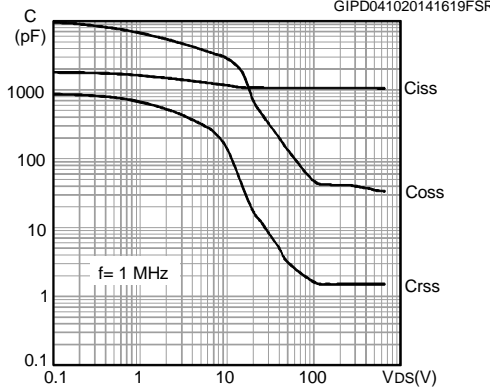


Figure 9: Normalized gate threshold voltage vs temperature

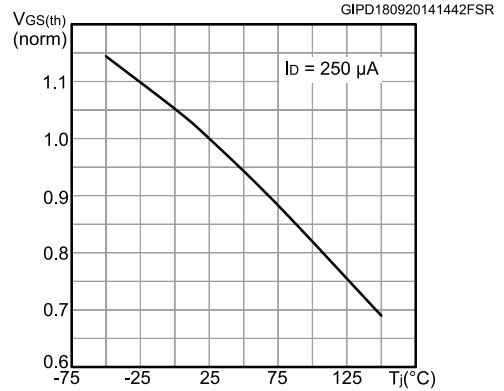


Figure 10: Normalized on-resistance

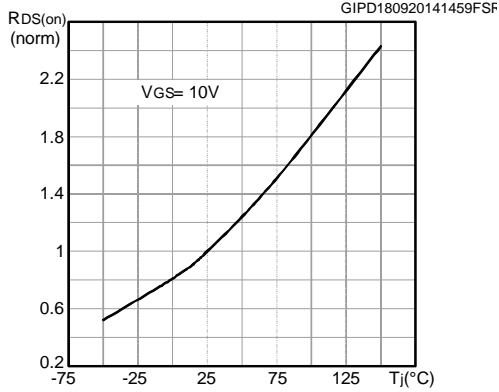


Figure 11: Normalized V(BR)DSS vs temperature

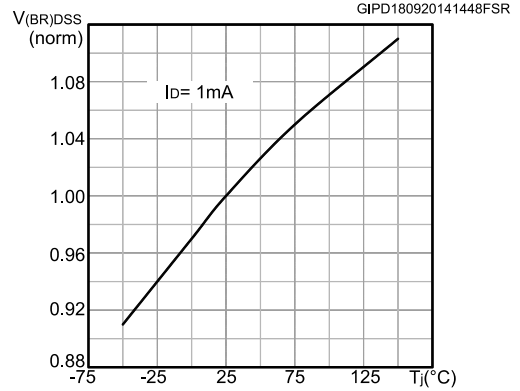


Figure 12: Source-drain diode forward characteristics

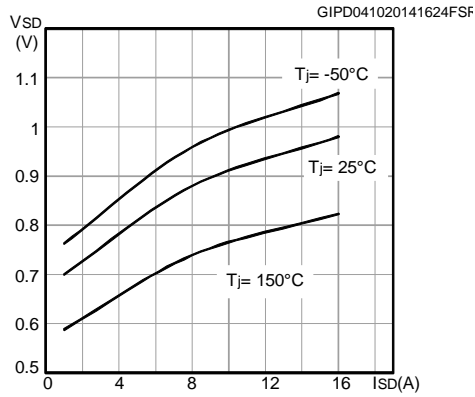
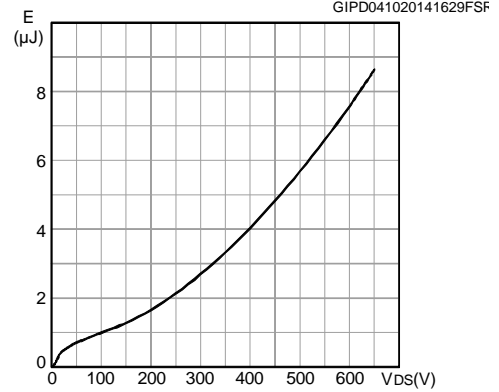
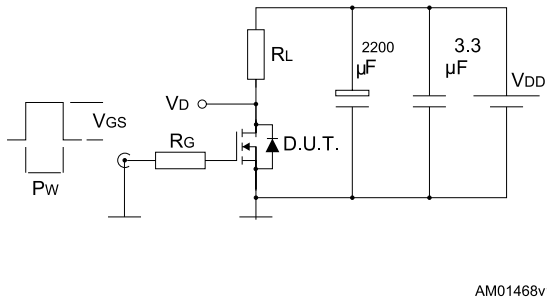


Figure 13: Output capacitance stored energy

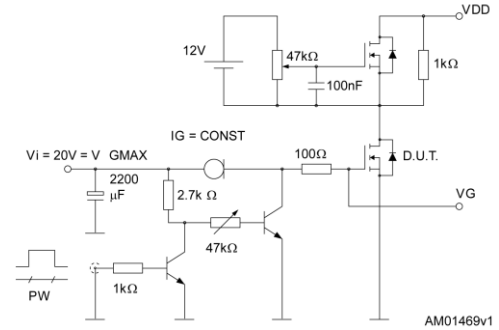


### 3 Test circuits

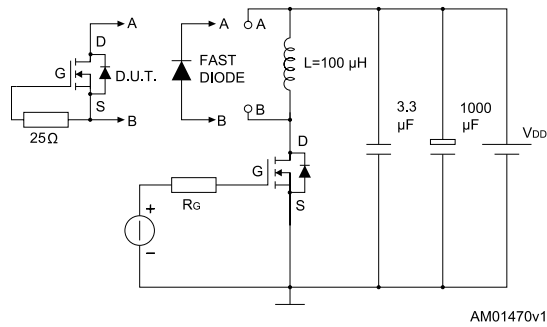
**Figure 14: Switching times test circuit for resistive load**



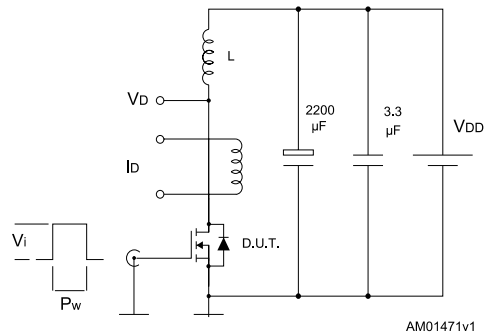
**Figure 15: Gate charge test circuit**



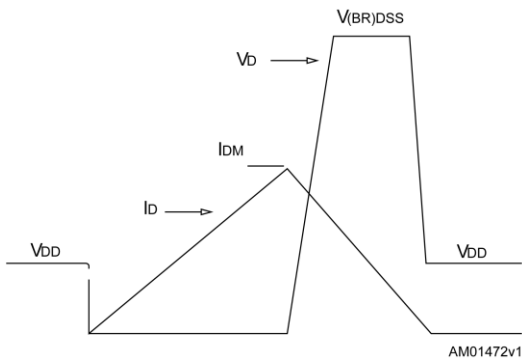
**Figure 16: Test circuit for inductive load switching and diode recovery times**



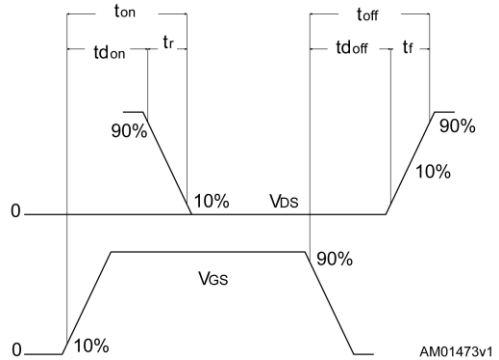
**Figure 17: Unclamped inductive load test circuit**



**Figure 18: Unclamped inductive waveform**



**Figure 19: Switching time waveform**





## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 4.1 PowerFLAT 8x8 HV package information

Figure 20: PowerFLAT™ 8x8 HV drawing

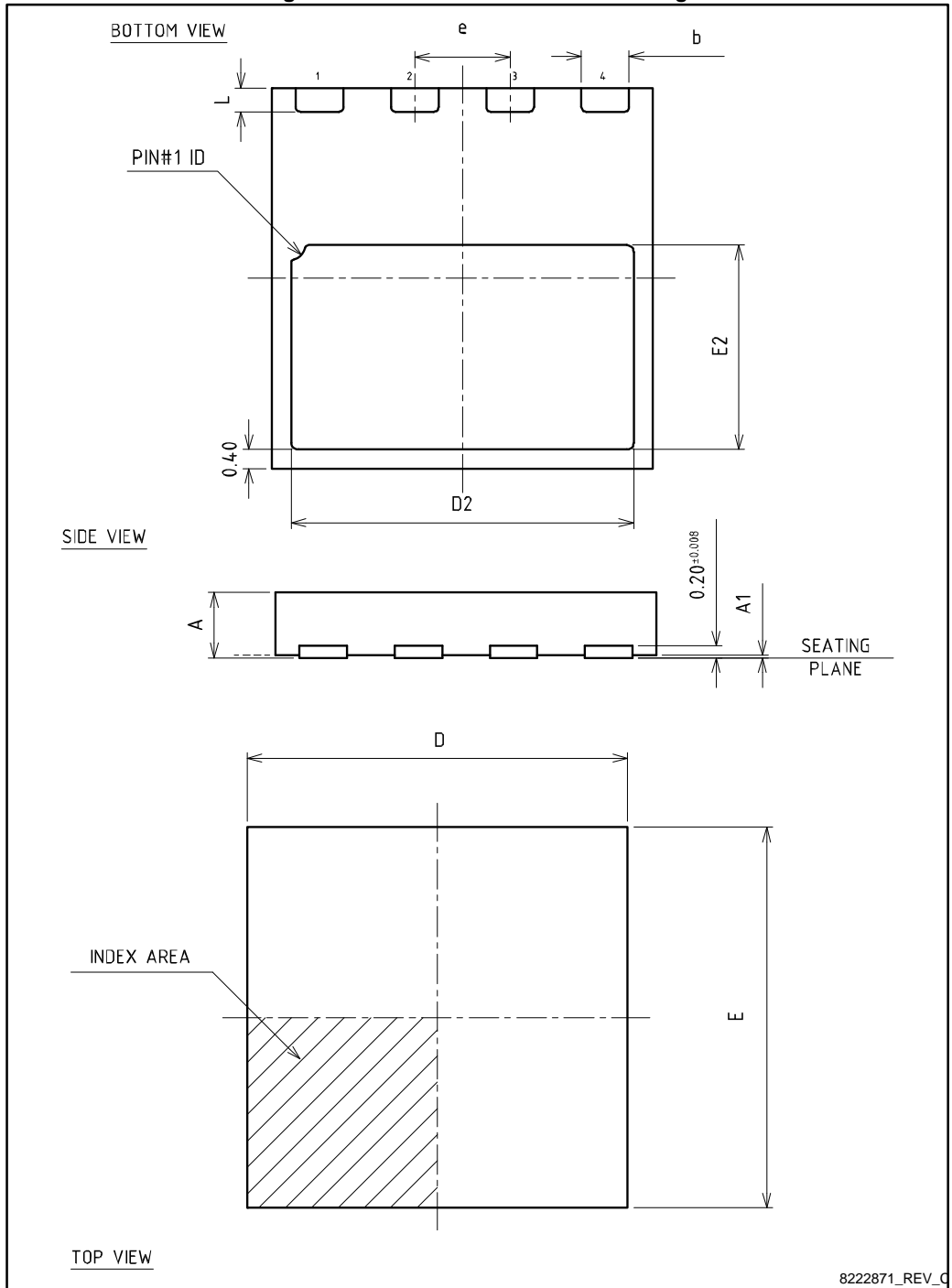
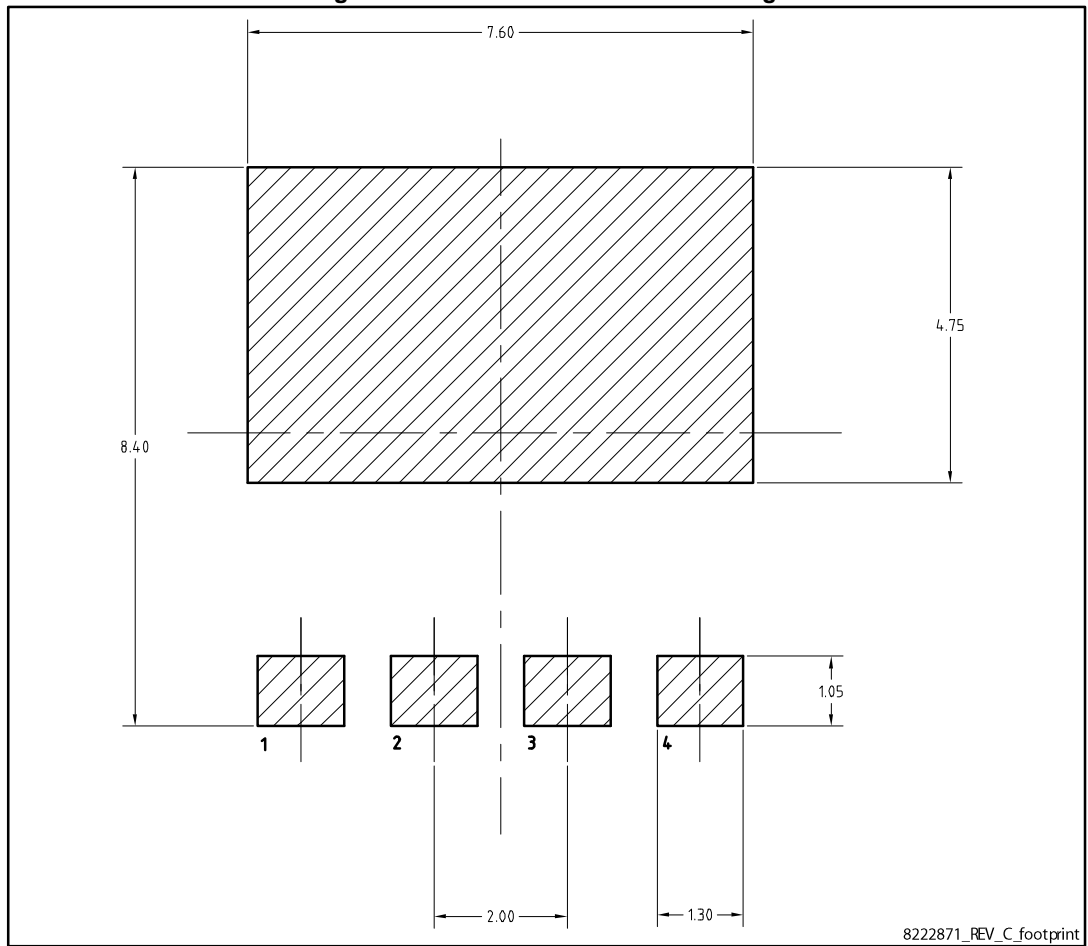


Table 9: PowerFLAT™ 8x8 HV mechanical data

| Dim. | mm    |      |      |
|------|-------|------|------|
|      | Min.  | Typ. | Max. |
| A    | 0.80  | 0.90 | 1.00 |
| A1   | 0.00  | 0.02 | 0.05 |
| b    | 0.95  | 1.00 | 1.05 |
| D    |       | 8.00 |      |
| E    |       | 8.00 |      |
| D2   | 7.05  | 7.20 | 7.30 |
| E2   | 4.155 | 4.30 | 4.40 |
| e    |       | 2.00 |      |
| L    | 0.40  | 0.50 | 0.60 |

Figure 21: PowerFLAT™ 8x8 HV drawing



All the dimensions are in millimeters.

# 5 Packaging mechanical data

Figure 22: PowerFLAT™ 8x8 HV tape

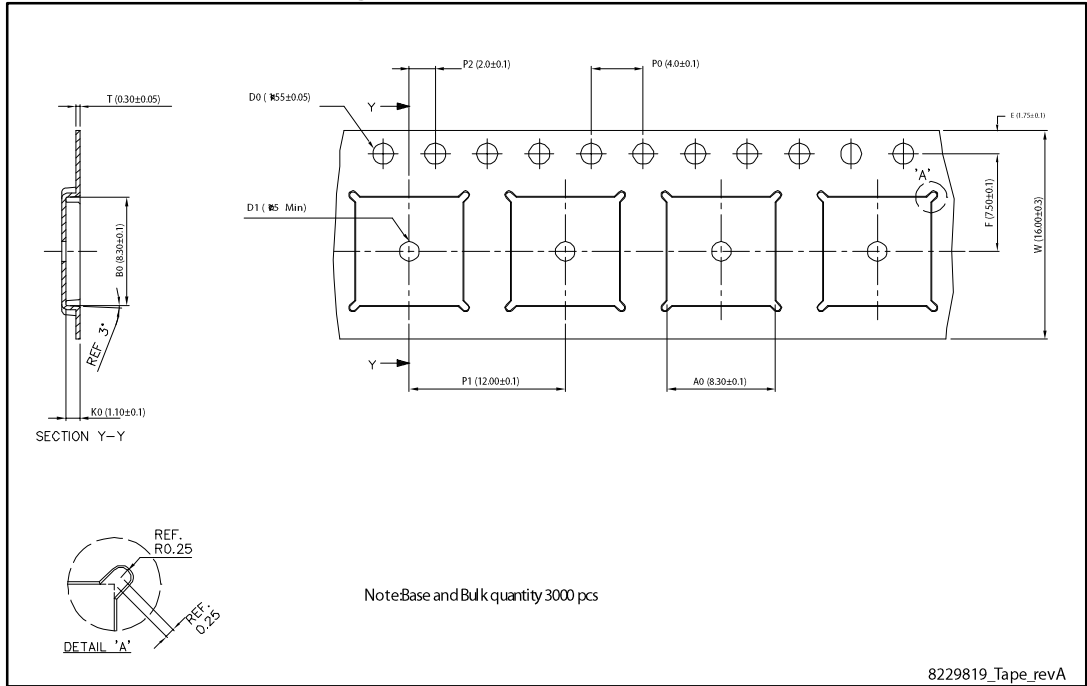


Figure 23: PowerFLAT™ 8x8 HV package orientation in carrier tape

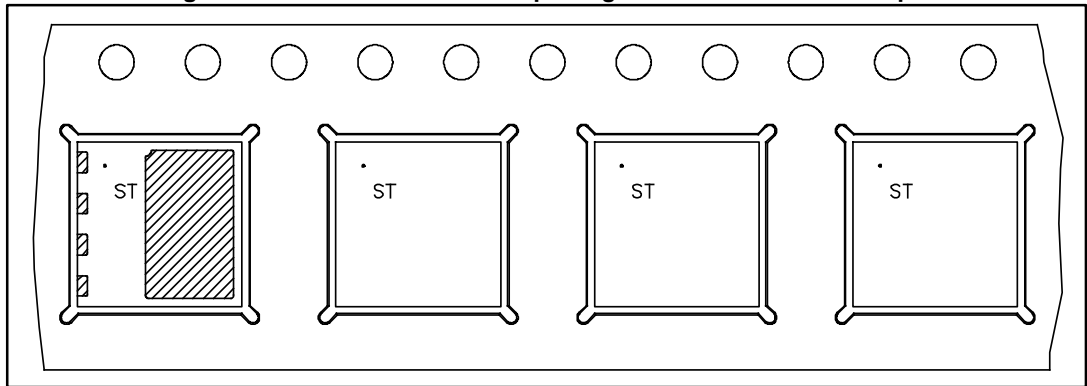
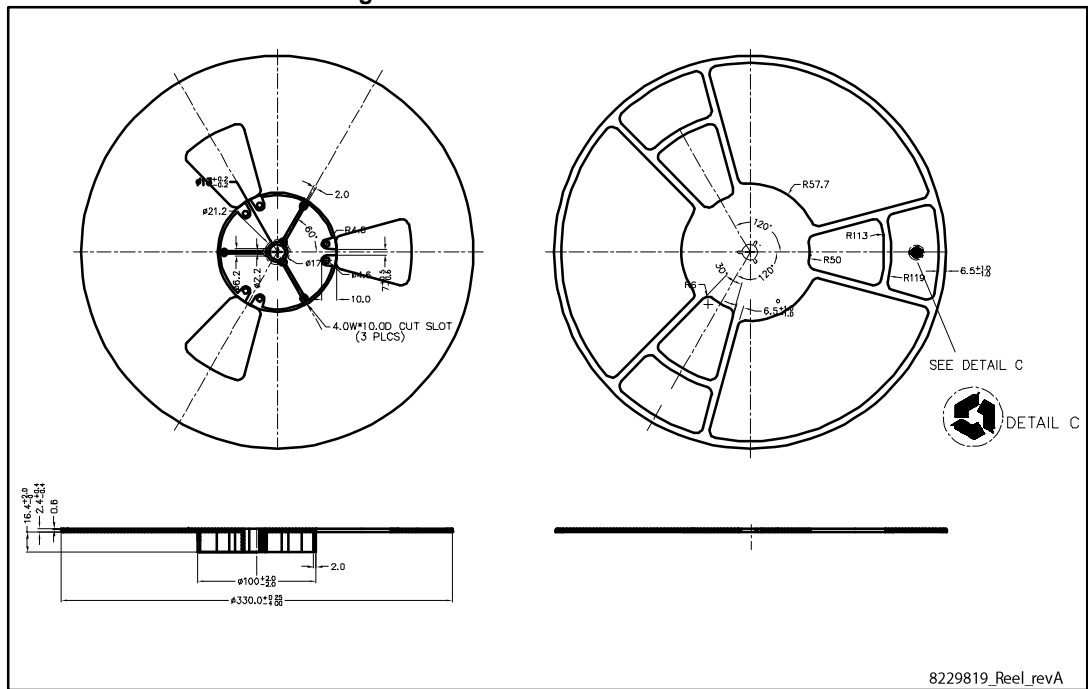


Figure 24: PowerFLAT™ 8x8 HV reel



## 6 Revision history

Table 10: Document revision history

| Date        | Revision | Changes        |
|-------------|----------|----------------|
| 19-Nov-2014 | 1        | First release. |

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